

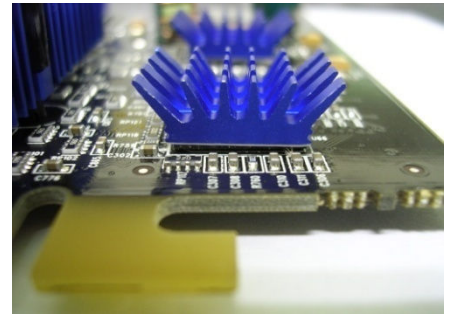
# CSC THERMAL CONDUCTIVE PAD

## TP-H3000 Series

### Description & Applications

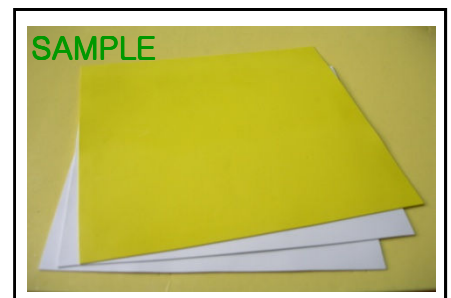
TP-H3000 is designed as a specially high thermal conductive materials. The high thermal conductivity allows the pads to apply to high-end electronic devices. These material is for applications where optimal heat transfer is requirement.

- CPUs, Graphic Cards
- High Power Components (Power Transistor)
- Wireline/Wireless Communications Devices



### Main Features

- Thermal conductivity = 3.0 ~ 3.5 W/mK
- Specially high thermal performance
- Moderate hardness
- Electrically insulating



### Specifications

ITEM	TP-H3000	METHOD
<b>Mechanical</b>		
Color*	Beige	Visual
Thickness (mm)	0.2 ~ 5.0	ASTM D374
Density (g/cc)	2.20	ASTM D792
Hardness (Shore A)	79	ASTM D2240
Tensile Strength (kgf/cm <sup>2</sup> )	16.1	ASTM D412
Use Temp. (°C)	-60 ~ 200	-
<b>Electrical</b>		
Dielectric Breakdown Voltage (V)	> 6,000	ASTM D149
Volume Resistivity (Ω · cm)	10 <sup>13</sup>	ASTM D257
<b>Thermal</b>		
Thermal Conductivity (W/mK)	3.0	ASTM C518-98 (Modified)
Flame Rating (UL94)	V-0	File No. E258204

※ Pad color can be adjustable upon request